

Attorney Docket No. 5649-958

### **PATENT**

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Lee et al. Serial No.: 10/085,369

Group Art Unit: 2818 Examiner: Thao P. Le Confirmation No.: 6590

Filed: February 28, 2002 For:

METHODS OF FABRICATING READ ONLY MEMORY DEVICES

INCLUDING THERMALLY OXIDIZED TRANSISTOR SIDEWALLS

AND DEVICES SO FABRICATED

April 29, 2003

**Box NON-FEE AMENDMENT** Commissioner for Patents Washington, DC 20231

### **AMENDMENT**

Sir:

This Amendment is responsive to the Restriction Requirement of April 9, 2003

# In the Title:

Please delete the title in all occurrences and substitute the following title therefor: --METHODS OF FABRICATING READ ONLY MEMORY DEVICES INCLUDING THERMALLY OXIDIZED TRANSISTOR SIDEWALLS--.

### In the Claims:

Please cancel Claims 14-19 without prejudice to the filing of a divisional application.

#### REMARKS

In response to the Restriction Requirement of April 9, 2003, Applicants hereby elect Invention II, corresponding to Claims 1-13, drawn to a method of adhering copper thin film to a substrate. Applicants have canceled Invention I, corresponding to Claims 14-19, drawn to an integrated circuit having a copper interconnect. This cancellation is being made without prejudice to the filing of a divisional application for these claims.